



**Spec No.: DS-70-97-0013** Effective Date: 01/26/2016

Revision: H

**LITE-ON DCC** 

**RELEASE** 

BNS-OD-FC001/A4

### LITE-ON Technology Corp. / Optoelectronics

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### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 1. DESCRIPTION

#### 1.1 Features

- Current transfer ratio (CTR : MIN. 50% at I<sub>F</sub> = 5mA, V<sub>CE</sub> = 5V)
- High input-output isolation voltage (V<sub>iso</sub> = 5,000Vrms)
- Response time (tr : TYP.  $4\mu s$  at  $V_{CE} = 2V$ ,  $I_C = 2mA$ ,  $R_L = 100\Omega$ )
- Dual-in-line package :

LTV-816: 1-channel type

LTV-826: 2-channel type

LTV-846: 4-channel type

■ Wide lead spacing package :

LTV-816M: 1-channel type

LTV-826M: 2-channel type

LTV-846M: 4-channel type

Surface mounting package :

LTV-816S: 1-channel type

LTV-826S: 2-channel type

LTV-846S: 4-channel type

Tape and reel packaging :

LTV-816S -TA: 1-channel type

LTV-816S -TA1 : 1-channel type

LTV-816S -TP: 1-channel type

LTV-826S -TA: 2-channel type

LTV-826S -TA1 : 2-channel type

Safety approval

UL 1577

VDE DIN EN60747-5-5 (VDE 0884-5)

CSA CA5A

CQC GB4943.1-2011/ GB8898-2011 (meet Altitude up to 5000m)

Nordic Safety (FIMKO/NEMKO/SEMKO/DEMKO)

BSI

RoHS Compliance

All materials be used in device are followed EU RoHS directive (No.2002/95/EC).

- ESD pass HBM 8000V/MM2000V
- MSL class1

#### 1.2 Applications

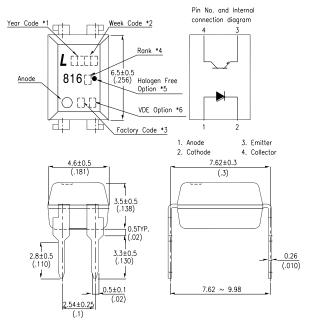
- Hybrid substrates that require high density mounting.
- Programmable controllers



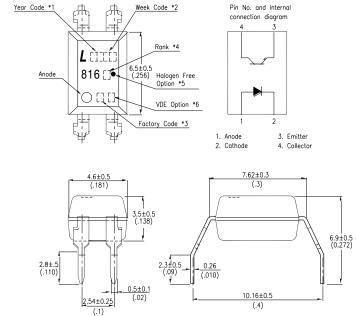
### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

### 2. PACKAGE DIMENSIONS

#### 2.1 LTV-816

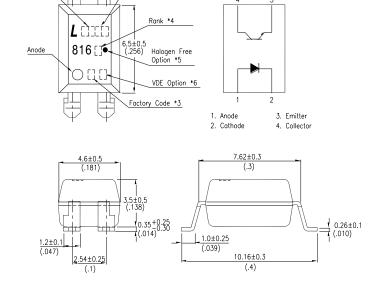


#### 2.2 LTV-816M



#### 2.3 LTV-816S

Year Code \*1



Pin No. and Internal connection diagram

#### Notes:

- 1. Year date code.
- 2. 2-digit work week.
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- 5. "●" for halogen free option.
- 6. "4"or"V" for VDE option.

Dimensions in millimeters (inches).

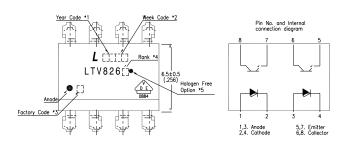


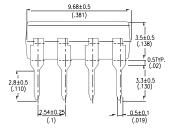
### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

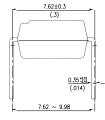
#### 2.4 LTV-826

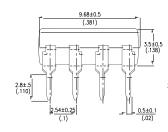
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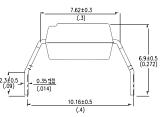
#### 2.5 LTV-826M



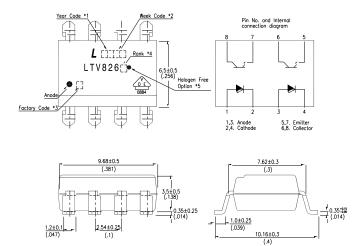








#### 2.6 LTV-826S



#### Notes:

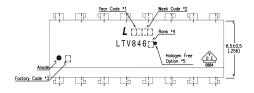
- 1. Year date code.
- 2. 2-digit work week.
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- 5. "●" for halogen free option.

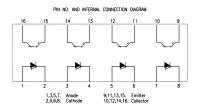
Dimensions in millimeters (inches).

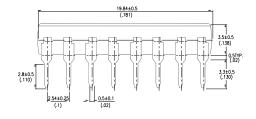


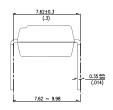
### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 2.7 LTV-846

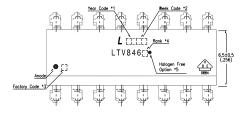


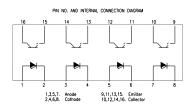


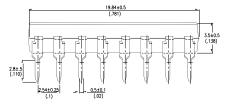


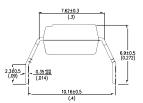


#### 2.8 LTV-846M

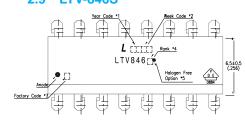


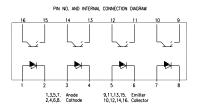


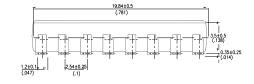


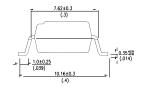


#### 2.9 LTV-846S









#### Notes:

- 1. Year date code.
- 2. 2-digit work week.
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- "●" for halogen free option.

Dimensions in millimeters (inches).

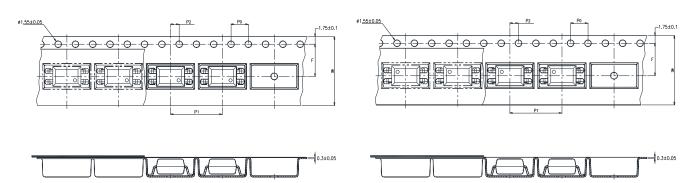


### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

### 3. TAPING DIMENSIONS

#### 3.1 LTV-816S-TA

### 3.2 LTV-816S-TA1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P <sub>0</sub>	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P <sub>2</sub>	2±0.1 (0.079)
Distance of compartment to compartment	P <sub>1</sub>	12±0.1 (0.472)

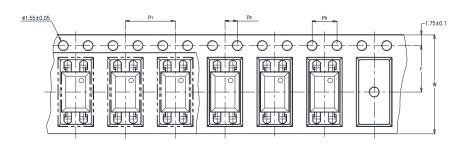
#### 3.3 Quantities Per Reel

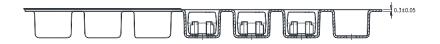
Package Type	TA/TA1
Quantities (pcs)	1000



### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 3.4 LTV-816S-TP





Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P <sub>0</sub>	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P <sub>2</sub>	2±0.1 (0.079)
Distance of compartment to compartment	P <sub>1</sub>	8±0.1 (0.472)

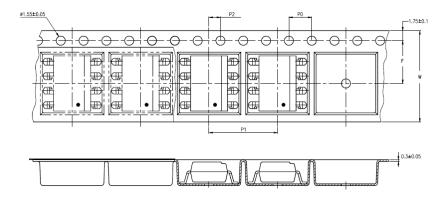
#### 3.5 Quantities Per Reel

Package Type	TP
Quantities (pcs)	2000

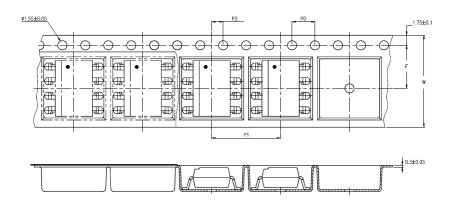


### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 3.6 LTV-826S-TA



#### 3.7 LTV-826S-TA1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P <sub>0</sub>	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
distance of compartment	P <sub>2</sub>	2±0.1 (0.079)
Distance of compartment to compartment	P <sub>1</sub>	12±0.1 (0.47)

#### 3.8 Quantities Per Reel

Package Type	TA/TA1
Quantities (pcs)	1000



### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 4. RATING AND CHARACTERISTICS

#### 4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
	Forward Current	l <sub>F</sub>	50	mA
lanut	Reverse Voltage	$V_R$	6	V
Input	Power Dissipation	Р	70	mW
	Junction Temperature	TJ	125	°C
	Collector - Emitter Voltage	V <sub>CEO</sub>	80	V
Output	Emitter - Collector Voltage	V <sub>ECO</sub>	6	V
Output	Collector Current		50	mA
	Collector Power Dissipation	Pc	150	mW
	Total Power Dissipation	P <sub>tot</sub>	200	mW
1.	Isolation Voltage	V <sub>iso</sub>	5000	$V_{rms}$
	Operating Temperature (LTV-826/846)	$T_{opr}$	-30 ~ +100	°C
	Operating Temperature (LTV-816)	T <sub>opr</sub>	-50 ~ +110	°C
	Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C
2.	Soldering Temperature	T <sub>sol</sub>	260	°C

1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

Parameter		Symbol	Min.	Тур.	Max.	Unit	Test Condition
	Forward Voltage	V <sub>F</sub>	_	1.2	1.4	V	I <sub>F</sub> =20mA
Input	Reverse Current	I <sub>R</sub>	_	_	10	μА	V <sub>R</sub> =4V
	Terminal Capacitance	Ct	_	30	250	pF	V=0, f=1KHz
	Collector Dark Current	I <sub>CEO</sub>	_	_	100	nA	V <sub>CE</sub> =20V, I <sub>F</sub> =0
Output	Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	80	_	_	V	I <sub>C</sub> =0.1mA, I <sub>F</sub> =0
	Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	6	_	_	V	I <sub>E</sub> =10μΑ, I <sub>F</sub> =0
	Collector Current	Ic	2.5	_	30	mA	L 5 m A \/ 5\/
	Current Transfer Ratio	CTR	50	_	600	%	I <sub>F</sub> =5mA, V <sub>CE</sub> =5V
	Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_	0.1	0.2	V	I <sub>F</sub> =20mA, I <sub>C</sub> =1mA
TRANSFER	Isolation Resistance	R <sub>iso</sub>	5×10 <sup>10</sup>	1×10 <sup>11</sup>	_	Ω	DC500V, 40 ~ 60% R.H.
CHARACTERISTICS	Floating Capacitance	Cf	_	0.6	1	pF	V=0, f=1MHz
	Cut-off Frequency	f <sub>c</sub>	_	80	_	kHz	VCE=5V, IC=2mA RL=100Ω,-3dB
	Response Time (Rise)	tr	_	4	18	μS	V <sub>CE</sub> =2V, I <sub>C</sub> =2mA
	Response Time (Fall)	tf	_	3	18	μS	$R_L$ =100 $\Omega$ ,

1. 
$$CTR = \frac{I_C}{I_F} \times 100\%$$



## Photocoupler LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

### 5. RANK TABLE OF CURRENT TRANSFER RATIO

	CTR Rank	Min	Max	Condition
	L	50	100	
	А	80	160	
LTV-816	В	130	260	
L1 V-010	С	200	400	
	D	300	600	
	L or A or B or C or D 50 600	600		
	No Bin	50	600	I <sub>F</sub> =5mA, V <sub>CE</sub> =5V, Ta=25°C
LTV-826	В	130	260	IF-SITIA, VCE-SV, Id-25 C
	С	200	400	
	ВС	130	400	
	CD	200	600	
	No Bin	50	600	
LTV-846	ВС	130	400	
	CD	200	600	

80

100

120



### **Photocoupler**

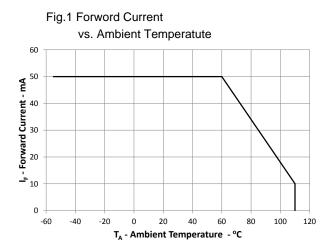
### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

0

-60

-40

### **CHARACTERISTICS CURVES**



vs. Ambient Temperature 160 - mW P<sub>c</sub> - Collecter Power Dissipation

T<sub>A</sub> - Ambient Temperature - °C

Fig.3 Collector-emitter Saturation Voltage vs. Forward Current

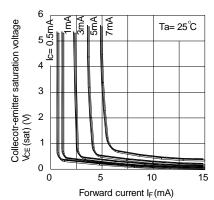


Fig.4 Forward Current vs. Forward Voltage

Fig.2 Collector Power Dissiption

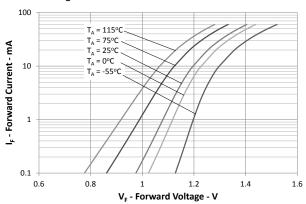


Fig.5 Normalized CTR vs. Forward Current

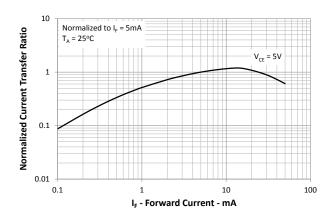
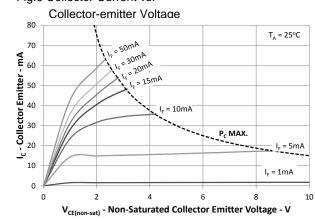


Fig.6 Collector Current vs.





### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

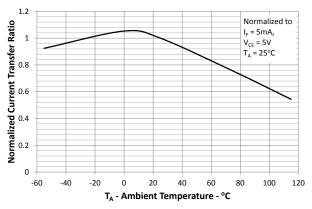


Fig.9 Collector Dark Current vs. Ambient Temperature

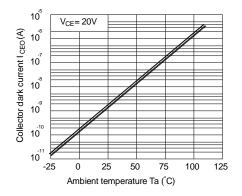


Fig.11 Frequency Response

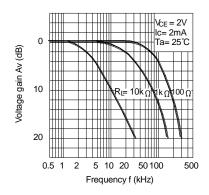


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

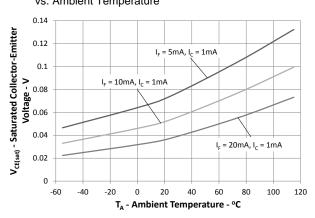
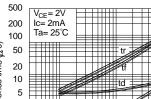
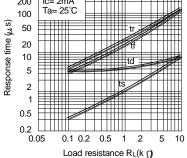
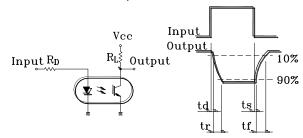


Fig.10 Response Time vs. Load Resistance

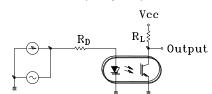




Test Circuit for Response Time



Test Circuit for Frequency Response





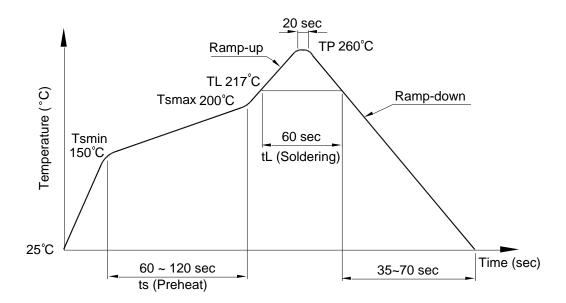
### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

### 7. TEMPERATURE PROFILE OF SOLDERING

### 7.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions
Preheat	
- Temperature Min (T <sub>Smin</sub> )	150°C
- Temperature Max (T <sub>Smax</sub> )	200°C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (T <sub>L</sub> )	217°C
- Time (t <sub>L</sub> )	60 sec
Peak Temperature (T <sub>P</sub> )	260°C
Ramp-up rate	3°C / sec max.
Ramp-down rate	3~6°C / sec





### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 7.2 Wave soldering (JEDEC22A111 compliant)

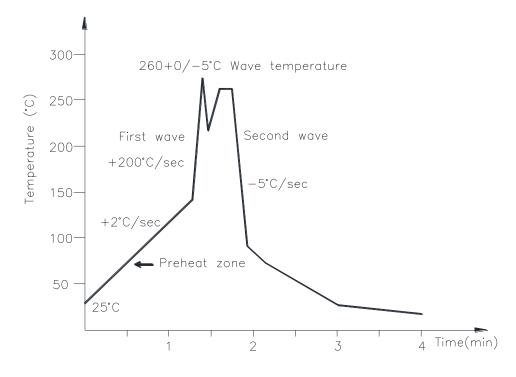
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



#### 7.3 Hand soldering by soldering iron

Temperature: 380+0/-5°C

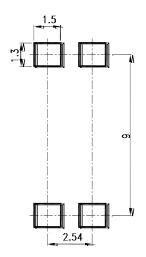
Time: 3 sec max.



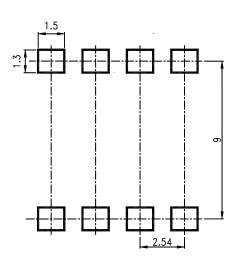
### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

### 8. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

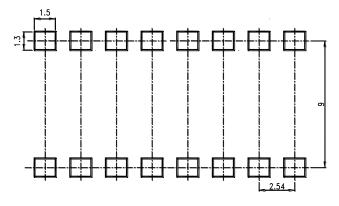
#### 8.1 4 PIN



#### 8.2 8 PIN



#### 8.3 16PIN



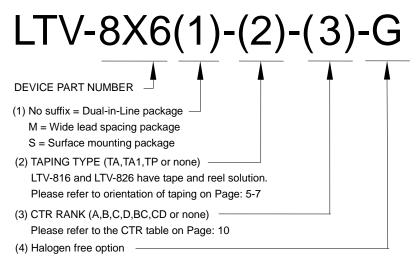
### Note:

Dimensions in millimeters.

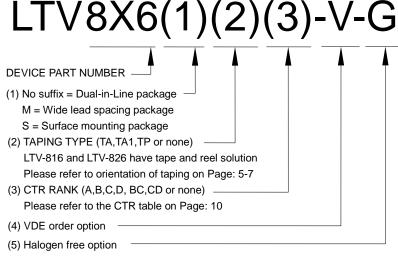


LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

### 9. Naming rule



Example: LTV-816S-TA1-A-G, LTV-846S-BC



Example: LTV816STA1A-V-G, LTV846SBC-V



### LTV-816 826 846 (M, S, S-TA, S-TA1, S-TP) Series

#### 10. Notes:

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.
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